

App. No. : 10/005,024  
Filed : December 4, 2001

### AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph on page 28, lines 15 to 23 with the paragraph below.

Arbitrarily, pad 121 is generally assigned ground potential and pad 122 is assigned power. A first (upper) flexible circuit 116 is provided with either a continuous raised strip or a set of individual raised bump contacts 117 which electrically engage with the pad 121 on interposer 120. The strip 117 or individual contact bumps can be formed as a part of the flexible circuit 116 using either electro-plating methods or formed and solder joined contacts as currently practiced in the industry. In a similar manner, a lower flexible circuit 115 is also provided with a continuous raised strip ~~117~~ 115 or individual contact bumps. In the illustrated embodiment, each flexible circuit 116, 117 carries only one polarity of power, e.g., ground and power.

Please replace the paragraph on page 28, line 24 to page 29, line 3 with the paragraph below.

Pressure is applied to the contact area (the junction between ~~interposer~~ ground pad 121 and strip/contact 117) utilizing compressible members 118 such as elastomeric pads residing in a cavity 202 formed by the upper housing 112 and the lower housing 113. Although shown as an elastomeric pad it is also possible to utilize a spring finger strip which can be located in the same area as the elastomeric pad 118 to provide a uniform pressure to the contact area. Upper flexible circuit 116 and lower flexible circuit 115 are joined to rigid circuit board 111 which provides a mounting structure for coaxial interconnects 110 and serves as a limit stop when inserting power interface assembly 11 into processor interposer 120.

Please replace the paragraph on page 31, lines 20 to 28 with the paragraph below.

After the flexible circuits 142 and 143 egress the housings 140 and 141 they are brought up to the first circuit board 101, which is a power regulator module, where the ends of each flexible circuit are interdigitated forming alternating soldered connection tabs 146 and ~~146~~147 which are soldered to corresponding alternating power and ground surface pads 144 and 145 on the lower surface of the first circuit board 101. This arrangement provides a low inductance connection due to the small loop area between the interdigitated connections comprising of pads 144 and 145, and simplifies solder assembly, since a simple bar solder operation on one side of

App. No. : 10/005,024  
Filed : December 4, 2001

the flexible circuits can be used to solder all of the tabs of the flexible circuits to the pads on the first circuit board (power regulator module) 101.